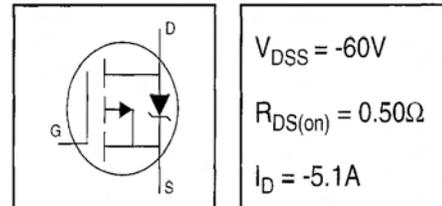


IRFR9014PbF

IRFU9014PbF

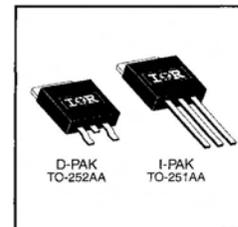
- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- Surface Mount (IRFR9014)
- Straight Lead (IRFU9014)
- Available in Tape & Reel
- P-Channel
- Fast Switching
- Lead-Free



Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D-Pak is designed for surface mounting using vapor phase, infrared, or wave soldering techniques. The straight lead version (IRFU series) is for through-hole mounting applications. Power dissipation levels up to 1.5 watts are possible in typical surface mount applications.



Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D @ T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ -10\text{ V}$	-5.1	A
$I_D @ T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ -10\text{ V}$	-3.2	
I_{DM}	Pulsed Drain Current ①	-20	
$P_D @ T_C = 25^\circ\text{C}$	Power Dissipation	25	W
$P_D @ T_A = 25^\circ\text{C}$	Power Dissipation (PCB Mount)**	2.5	
	Linear Derating Factor	0.20	
	Linear Derating Factor (PCB Mount)**	0.020	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy ②	140	mJ
I_{AR}	Avalanche Current ①	-5.1	A
E_{AR}	Repetitive Avalanche Energy ①	2.5	mJ
dv/dt	Peak Diode Recovery dv/dt ③	-4.5	V/ns
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to +150	°C
	Soldering Temperature, for 10 seconds	260 (1.6mm from case)	

Thermal Resistance

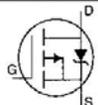
	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	—	5.0	°C/W
$R_{\theta JA}$	Junction-to-Ambient (PCB mount)**	—	—	50	
$R_{\theta JA}$	Junction-to-Ambient	—	—	110	

** When mounted on 1" square PCB (FR-4 or G-10 Material).

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	-60	—	—	V	$V_{GS}=0V, I_D=-250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	-0.059	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D=-1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.50	Ω	$V_{GS}=-10V, I_D=-3.1A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	-2.0	—	-4.0	V	$V_{DS}=V_{GS}, I_D=-250\mu A$
g_{fs}	Forward Transconductance	1.4	—	—	S	$V_{DS}=-25V, I_D=-3.1A$ ④
I_{DSS}	Drain-to-Source Leakage Current	—	—	-100	μA	$V_{DS}=-60V, V_{GS}=0V$
		—	—	-500		$V_{DS}=-48V, V_{GS}=0V, T_J=125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	-100	nA	$V_{GS}=20V$
	Gate-to-Source Reverse Leakage	—	—	100		$V_{GS}=20V$
Q_g	Total Gate Charge	—	—	12	nC	$I_D=6.7A$
Q_{gs}	Gate-to-Source Charge	—	—	3.8		$V_{DS}=-48V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	5.1		$V_{GS}=-10V$ See Fig. 6 and 13 ④
$t_{d(on)}$	Turn-On Delay Time	—	11	—	ns	$V_{DD}=-30V$
t_r	Rise Time	—	63	—		$I_D=6.7A$
$t_{d(off)}$	Turn-Off Delay Time	—	9.6	—		$R_G=24\Omega$
t_f	Fall Time	—	31	—		$R_D=4.0\Omega$ See Figure 10 ④
L_D	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6 mm (0.25in.) from package and center of die contact
L_S	Internal Source Inductance	—	7.5	—		
C_{iss}	Input Capacitance	—	270	—	pF	$V_{GS}=0V$
C_{oss}	Output Capacitance	—	170	—		$V_{DS}=-25V$
C_{rss}	Reverse Transfer Capacitance	—	31	—		$f=1.0\text{MHz}$ See Figure 5

Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	—	—	-5.1	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	-20		
V_{SD}	Diode Forward Voltage	—	—	-5.5	V	$T_J=25^\circ\text{C}, I_S=-5.1A, V_{GS}=0V$ ④
t_{rr}	Reverse Recovery Time	—	80	160	ns	$T_J=25^\circ\text{C}, I_F=6.7A$
Q_{rr}	Reverse Recovery Charge	—	0.096	0.19	μC	$di/dt=100A/\mu s$ ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Notes:

① Repetitive rating; pulse width limited by max. junction temperature (See Figure 11)

③ $I_{SD} \leq 6.7A, di/dt \leq 90A/\mu s, V_{DD} \leq V_{(BR)DSS}, T_J \leq 150^\circ\text{C}$

② $V_{DD}=-25V$, starting $T_J=25^\circ\text{C}$, $L=6.3\text{mH}$, $R_G=25\Omega, I_{AS}=-5.1A$ (See Figure 12)

④ Pulse width $\leq 300 \mu s$; duty cycle $\leq 2\%$.

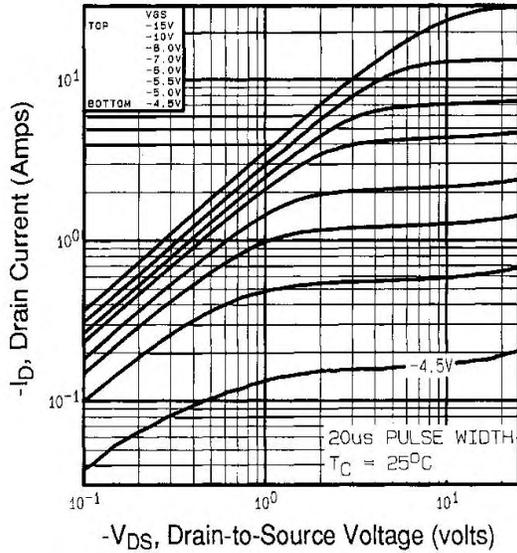


Fig 1. Typical Output Characteristics,
 $T_C=25^\circ\text{C}$

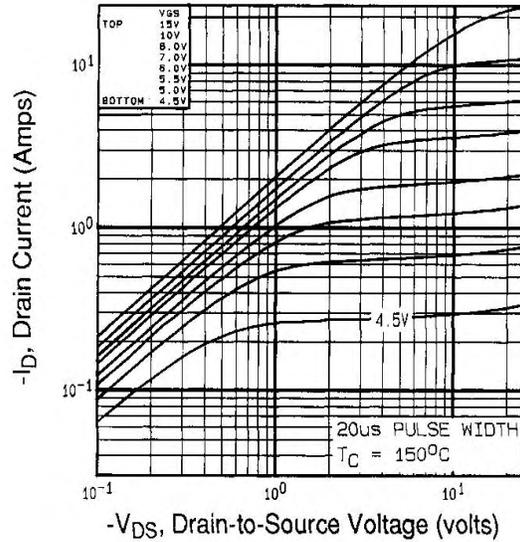


Fig 2. Typical Output Characteristics,
 $T_C=150^\circ\text{C}$

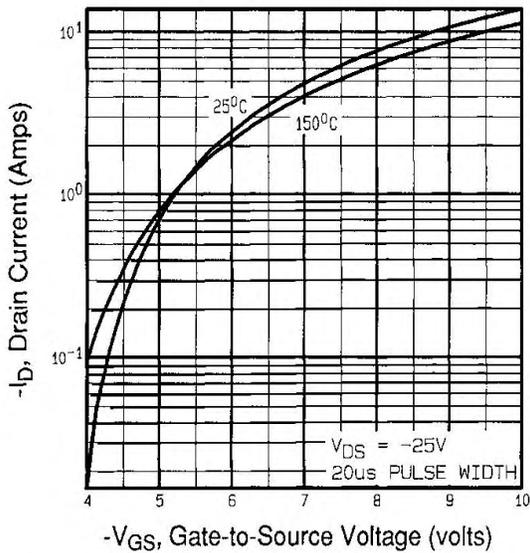


Fig 3. Typical Transfer Characteristics

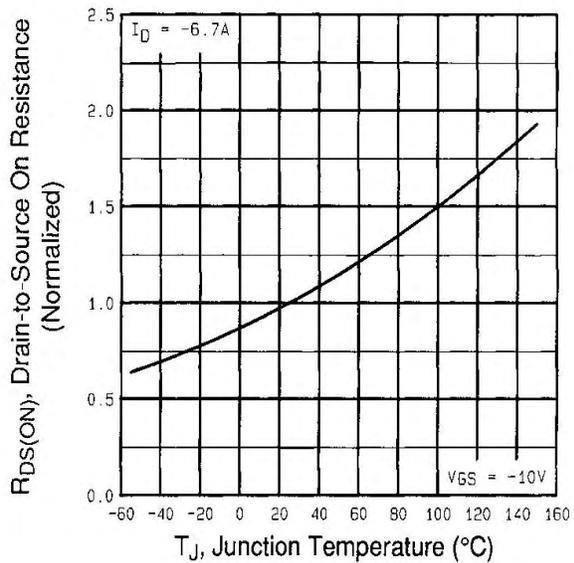


Fig 4. Normalized On-Resistance
Vs. Temperature

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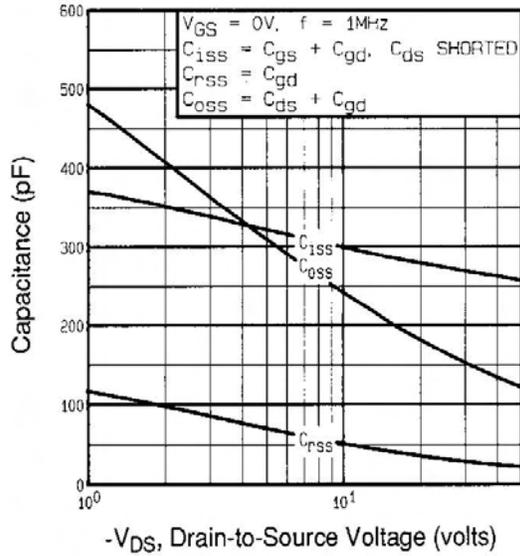


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

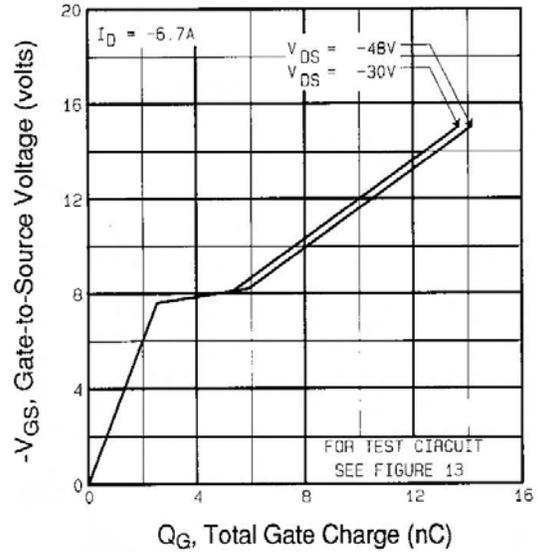


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

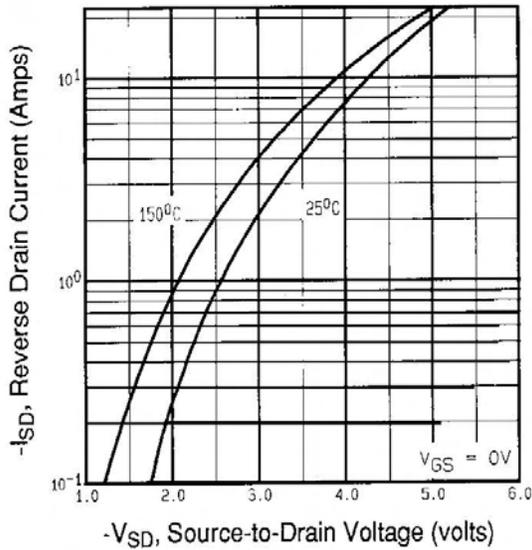


Fig 7. Typical Source-Drain Diode Forward Voltage

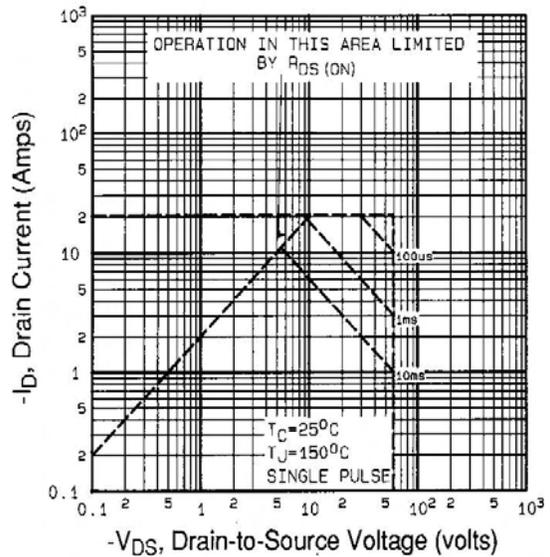


Fig 8. Maximum Safe Operating Area

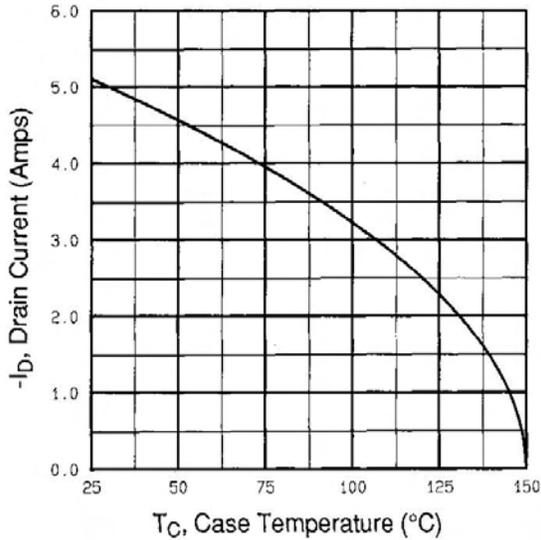


Fig 9. Maximum Drain Current Vs. Case Temperature

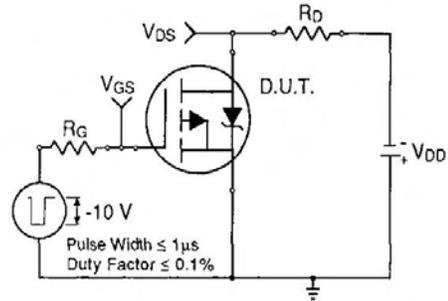


Fig 10a. Switching Time Test Circuit

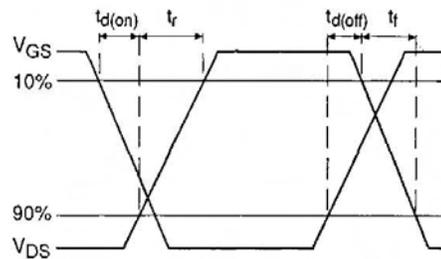


Fig 10b. Switching Time Waveforms

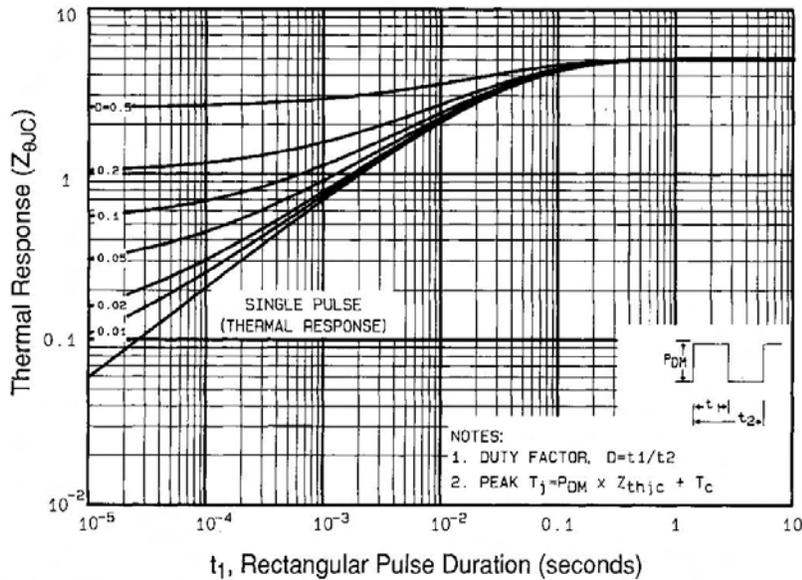


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

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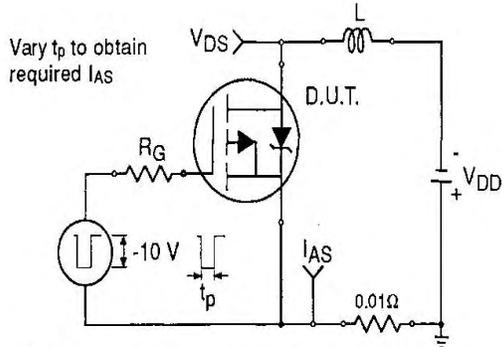


Fig 12a. Unclamped Inductive Test Circuit

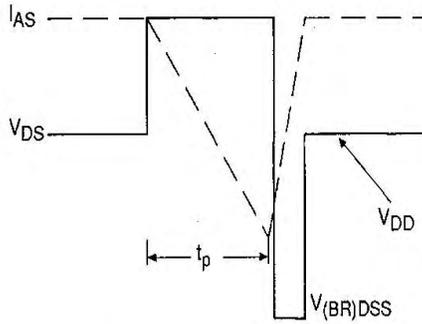


Fig 12b. Unclamped Inductive Waveforms

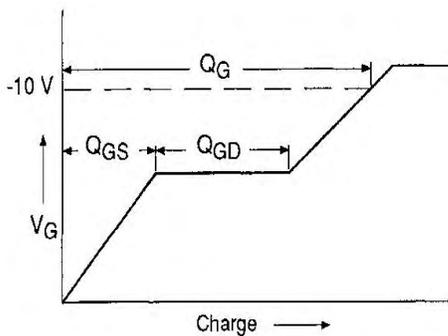


Fig 13a. Basic Gate Charge Waveform

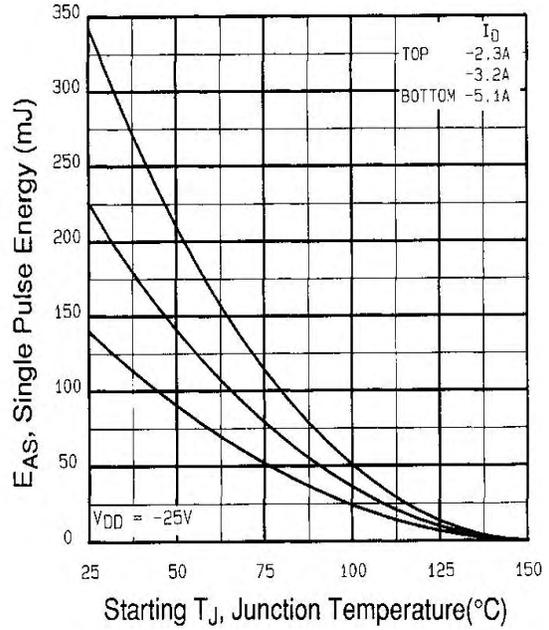


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

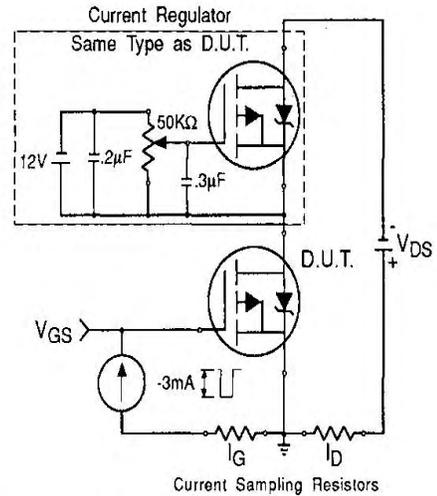


Fig 13b. Gate Charge Test Circuit

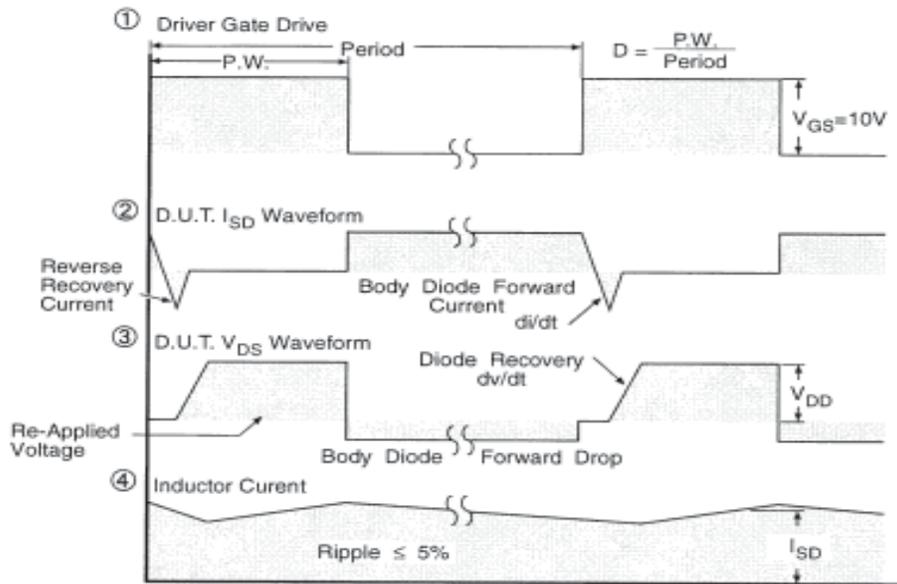
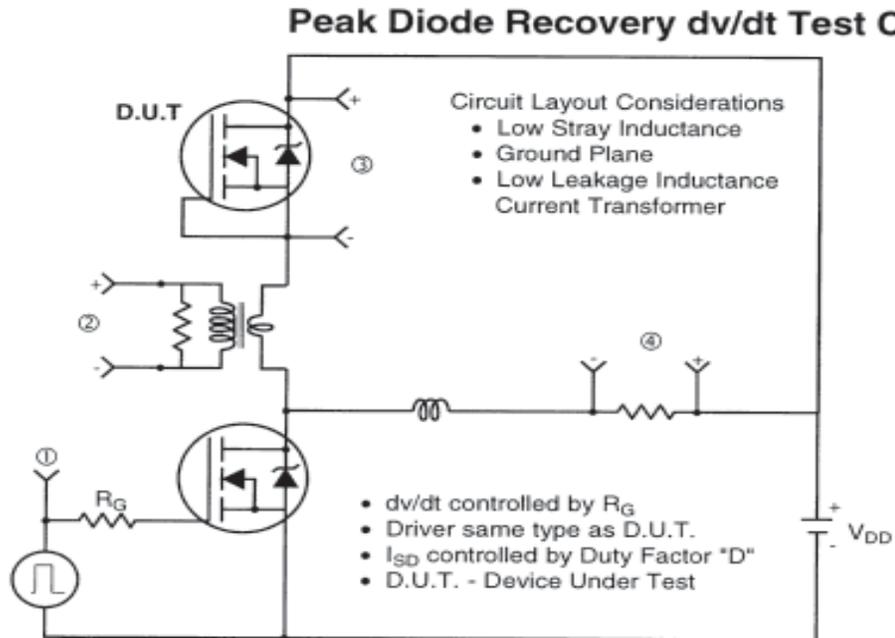


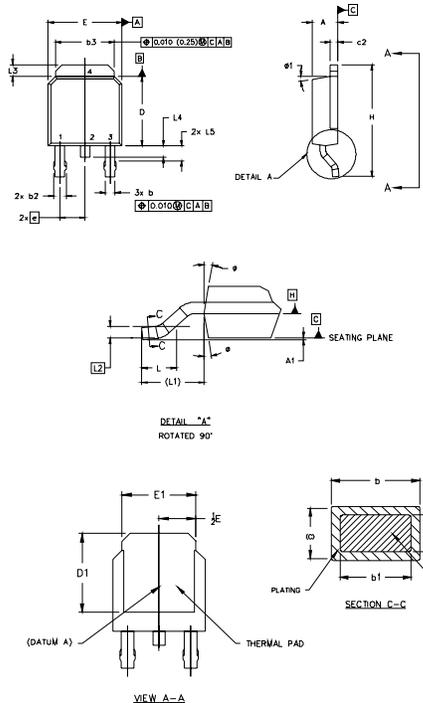
Fig 14. For N-Channel HEXFETS

IRFR/U9014PbF



D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

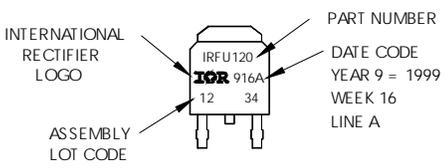
- 1.0 DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
- 2.0 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]
- 3.0 LEAD DIMENSION UNCONTROLLED IN L5
- 4.0 DIMENSION D1 AND E1 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
- 5.0 SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 [0.127] AND .010 [0.2540] FROM THE LEAD TIP.
- 6.0 DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 7.0 OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	.086	.094	
A1		0.13		.005	
b	0.64	0.89	.025	.035	5 LEAD ASSIGNMENTS
b1	0.64	0.79	.025	0.031	5
b2	0.76	1.14	.030	.045	HEXFEET
b3	4.95	5.46	.195	.215	
c	0.46	0.61	.018	.024	5 1.- GATE
c1	0.41	0.56	.016	.022	5 2.- DRAIN
c2	.046	0.89	.018	.035	5 3.- SOURCE
D	5.97	6.22	.235	.245	6 4.- DRAIN
D1	5.21	-	.205	-	4
E	6.35	6.73	.250	.265	6 IGBTs, CoPACK
E1	4.32	-	.170	-	4 1.- GATE
e	2.29	-	.090 BSC	-	2.- COLLECTOR
H	9.40	10.41	.370	.410	
L	1.40	1.78	.055	.070	
L1	2.74 REF.		.108 REF.		
L2	0.051 BSC		.020 BSC		
L3	0.89	1.27	.035	.050	
L4		1.02		.040	
L5	1.14	1.52	.045	.060	3
ø	Ø	1Ø	Ø	1Ø	
ø1	Ø	15'	Ø	15'	

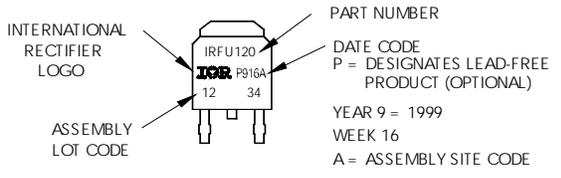
D-Pak (TO-252AA) Part Marking Information

EXAMPLE: THIS IS AN IRFR120 WITH ASSEMBLY LOT CODE 1234 ASSEMBLED ON WW16, 1999 IN THE ASSEMBLY LINE "A"

Note: "P" in assembly line position indicates "Lead-Free"



OR

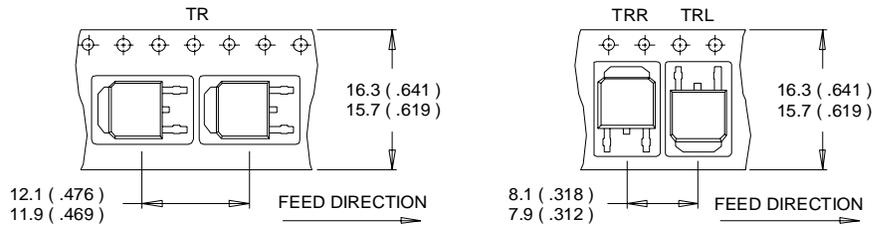


IRFR/U9014PbF

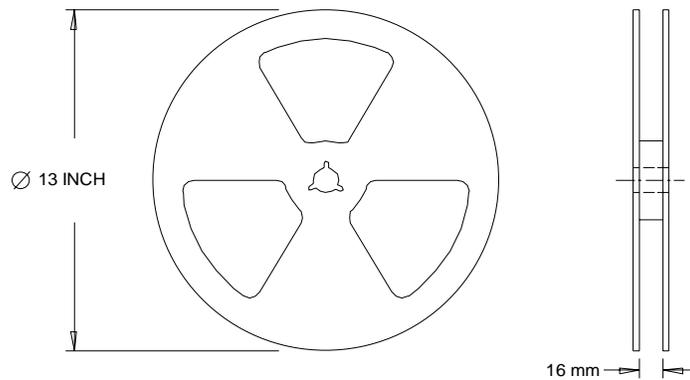
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D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



- NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES :
1. OUTLINE CONFORMS TO EIA-481.

Data and specifications subject to change without notice.

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IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105
TAC Fax: (310) 252-7903

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